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(54) Title: METHOD FOR ENCAPSULATING ELECTRONIC COMPONENTS WITH A CONTROLLABLE CLOSING FORCE

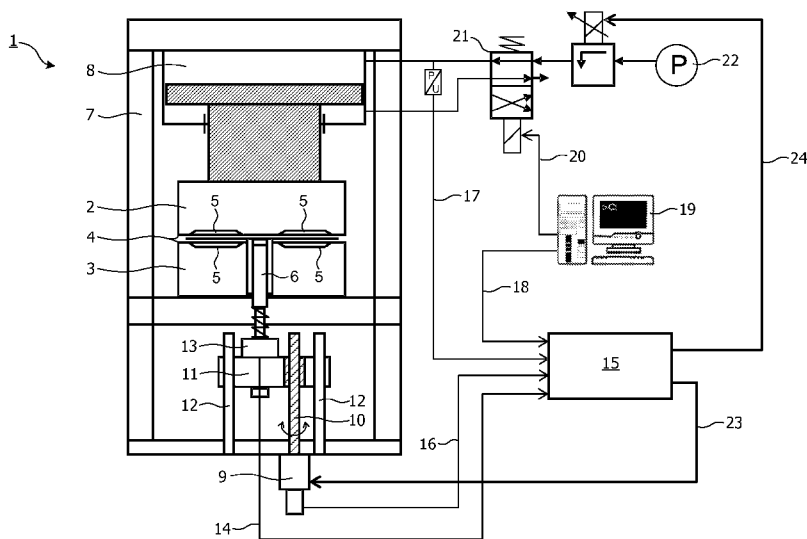


FIG. 1

(57) Abstract: The invention relates to a method for encapsulating electronic components mounted on a carrier, comprising the processing steps of: moving a number of mould parts (2, 3) toward each other with a closing force whereby the electronic component is enclosed by a mould cavity (5), exerting pressure on a liquid encapsulating material, filling the mould cavity (5) with encapsulating material, and curing the encapsulating material, wherein the pressure on the encapsulating material is measured, and the closing force of the mould parts and the exerted pressure are dependent on each other.



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